

B- 1. (Twice Amended) A metallurgical structure comprising:
a passivation layer;
a via through said passivation layer extending to a metal line within said metallurgical structure;
a barrier layer lining said via;
a metal plug in said via above said barrier layer, wherein said metal plug and said metal line comprise a same material, and wherein said metal plug, said barrier layer and said passivation layer form a planar exterior surface of said metallurgical structure; and
a solder bump formed on said planar exterior surface.

B- 8. (Twice Amended) An integrated circuit structure comprising:
internal components within an exterior covering;
a via extending through said exterior covering to said internal components;
a barrier layer lining said via;
a plug in said via above said barrier layer, wherein said plug and said internal components comprise a same material, and wherein said plug and said barrier layer form a planar exterior surface of said integrated circuit structure; and
a connector formed on said planar exterior surface.